



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

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10/10/02
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re the application of:

Donald C. Abbott et al.

Docket No.: TI-28098

Serial No: CPA of 09/525,105

Examiner: Williams, A.

Filed: 03/14/00

Art Unit: 2826

For: SEMICONDUCTOR CIRCUIT ASSEMBLY HAVING A PLATED
LEADFRAME INCLUDING GOLD SELECTIVELY COVERING AREAS
TO BE SOLDERED

INFORMATION DISCLOSURE STATEMENT

Assistant Commissioner for Patents
Washington, DC 20231

Dear Sir:

Please make the references listed on the enclosed PTO-1449 of record under 37 C.F.R. 1.56, 1.97, and 1.98 in the patent application identified above. Copies of the listed references are enclosed.

Respectfully submitted,

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